

Joffre 4		Corrosion Reliability of Electronics Devices and Materials
Chair(s)		<i>H. Schweigart / M.S. Jellesen</i>
13:40	O-69875	An overview on the corrosion reliability of electronics Rajan Ambat (Center for Electronic Corrosion, Materials and Surface Engineering, Department of Mechanical Engineering, Technical University of Denmark)
14:00	K-69885	Keynote Lecture Reliability of electrics and electronics in an automotive context; Examples addressing encapsulations and humidity dynamics Mats Ström (Volvo Car Group)
14:30	K-69930	Keynote Lecture Material and Process Influences on conductive anodic filament formation David Humby (Isola Group)
15:00	O-64497	Thermal effects in electronic systems: new results on electrochemical corrosion and their correlations Katharina Schultz (Robert Bosch GmbH) / Felix Petri (Robert Bosch GmbH)
15:20	O-69895	Interpretation of corrosion observed after IPC humidity test on PCB's with various flux types and electrical loads. Annemette Riis (Grundfos Holding A/S) / Allan Hjarbaek Holm (Grundfos Holding A/S) / John B. Jacobsen (Grundfos Holding A/S) / Jens Peter Krog (Grundfos Holding A/S) / Jakob Harming (Grundfos Holding A/S) / Lars Rimestad (Grundfos Holding A/S)
15:40	Coffee Break	
Joffre 4		Corrosion Reliability of Electronics Devices and Materials
Chair(s)		<i>R. Ambat / M.S. Jellesen</i>
16:10	O-50932	Procedure comparison for estimating the PCBA service life at moist climate exposure Helmut Schweigart (Dr. O.K. Wack Chemie GmbH)
16:30	O-52937	Investigation of the influence of electrochemical migration (ECM) on the reliability of electronic assemblies after rework using lead-free solders and No-clean flux mixtures Helge Schimanski (Fraunhofer-Institut für Siliziumtechnologie ISIT) / Olga Yezerska (Fraunhofer Institut fuer Fertigungstechnik und Angewandte Materialforschung-IFAM) / Peter Plagemann (Fraunhofer Institut fuer Fertigungstechnik und Angewandte Materialforschung- IFAM) / Jürgen Hagge (Fraunhofer-Institut für Siliziumtechnologie - ISIT)
16:50	O-62522	Characterization of humidity effects on electronics by means of impedance spectroscopy Vadimas Verdingovas (Technical University of Denmark (DTU)) / Morten Stendahl Jellesen (Technical University of Denmark) / Rajan Ambat (Technical University of Denmark)
17:10	O-59767	Electrochemical migration of Ni and ENIG surfaces finishes during thermal humidity bias test Bálint Medgyes (Budapest University of Technology and Economics (BME))

Joffre 4		Corrosion Reliability of Electronics Devices and Materials
Chair(s)		<i>R. Ambat / H. Schweigart</i>
8:40	O-60452	Effect of hygroscopic atmospheric particles deposition on the corrosion reliability of electronics Luca D'Angelo (University of Milano-Bicocca) / Verdingovas Vadimas (Technical University of Denmark, Department of Mechanical Engineering) / Luca Ferrero (University of Milano-Bicocca, Department of Earth and Environmental Science) / Ezio Bolzacchini (University of Milano-Bicocca, Department of Earth and Environmental Science) / Rajan Ambat (Technical University of Denmark, Department of Mechanical Engineering)
9:00	O-63832	Dynamics of moisture ingress in second and first level housings Helene Conseil (Technical University of Denmark) / Gerald Hamm (Robert Bosch GmbH, Automotive Electronics) / Lutz Müller (Robert Bosch GmbH, Automotive Electronics) / Mathias Hain (Robert Bosch GmbH, Automotive Electronics) / Rajan Ambat (Technical University of Denmark)
9:20	O-55312	Practical humidity ingress in electronic enclosures Kim Albert Schmidt (DELTA) / Anders Bonde Kentved (DELTA)
9:40	O-70090	Choosing the right No Clean chemistry for lead free solder paste in Vapor Phase Reflow Emmanuelle Guéné (Inventec Performance Chemicals)
10:00	O-64752	Simple standardized corrosion measurement of semiconductor metallizations Lutz Müller (Robert Bosch GmbH) / Johann Bartha (TU Dresden) / Sophie Louise Mach (TU Dresden)
10:20	Coffee Break	
Joffre 4		Corrosion Reliability of Electronics Devices and Materials
Chair(s)		<i>R. Ambat / H. Schweigart</i>
10:50	O-62342	Electronics device level testing and visualization of tin corrosion on printed circuit boards Morten Stendahl Jellesen (Technical University of Denmark) / Vadimas Verdingovas (DTU) / Helene Conseil (DTU) / Rajan Ambat (DTU)
11:10	O-60972	Degradation of wetness sensors exposed to maritime atmosphere Oleg Startsev (All-Russian Scientific-Research Institute of Aviation Materials) / Maksim Molokov (All-Russian Scientific-Research Institute of Aviation Materials) / Ivan Medvedev (All-Russian Scientific-Research Institute of Aviation Materials (FSUE))
11:30	O-59602	Thermal stability of electroplated tin-nickel alloy: study on microstructure and electrochemical propert Peter Jensen (Department of Mechanical Engineering, Technical University of Denmark) / Visweswara C. Gudla (Department of Mechanical Engineering, Technical University of Denmark) / Rajan Ambat (Department of Mechanical Engineering, Technical University of Denmark)
11:50	P-59512	Corrosion failure analysis of hearing aid battery-spring contacts Visweswara Gudla (Section of Materials and Surface Engineering, Department of Mechanical Engineering, Technical University of Denmark) / Morten Jellesen (Section of Materials and Surface Engineering, Department of Mechanical Engineering, Technical University of Denmark) / Rajan Ambat (Section of Materials and Surface Engineering, Department of Mechanical Engineering, Technical University of Denmark)
12:30	Lunch	